

1 **ABSTRACT OF THE DISCLOSURE**

2 The present invention relates a printed circuit board having jumper
3 lines, and a method for making the printed circuit board. An isolation layer
4 made of a dielectric material is coated on the line layer of the printed circuit
5 board, and multiple pads are formed in the isolation layer, thereby exposing
6 part of the line layer without covered by the isolation layer. A high conductive
7 material is coated on the isolation layer to connect the multiple pads, thereby
8 forming a planar jumper layer that is connected to the line layer through the
9 circular pads. Thus, the planar jumper layer may be made simultaneously
10 during fabrication of the printed circuit board, without having to perform the
11 wire-bonding work.

05955971-110704
FOI/DOJ-T/658650